

TOSHIBA BiCD Integrated Circuit Silicon Monolithic

TB67S128FTG

CLOCK-in and Serial controlled Bipolar Stepping Motor Driver

1. Outline

The TB67S128FTG is a two-phase bipolar stepping motor driver using a PWM chopper. The clock in decoder is built in.

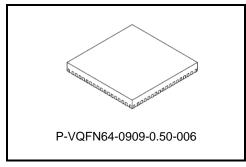
Fabricated with the BiCD process, output rating is 50 V/5.0 A (Motor supply voltage = 44 V).

2. Features

- BiCD process integrated monolithic IC.
- Capable of controlling 1 bipolar stepping motor.
- PWM controlled constant-current drive
- Low on-resistance (High + Low side = 0.25Ω (typ.)) MOSFET output stage.
- Allows full, half, quarter, 1/8, 1/16, 1/32, 1/64, 1/128 step operation.
- High efficiency motor current control mechanism (ADMD: Advanced Dynamic Mixed Decay)
- Built-in Anti-stall architecture (AGC: Active Gain Control)
- Built-in Sense resistor less current control architecture (ACDS: Advanced Current Detection System)
- High voltage and current (For specification, please refer to absolute maximum ratings and operation ranges)
- Multi error detect functions (Thermal shutdown (TSD), Over current (ISD), Power-on-reset (POR), motor load open (OPD)).
- Error detection (TSD/ISD/OPD) flag output function
- Built-in VCC regulator for internal circuit
- Chopping frequency of a motor can be adjusted by external resistance and capacitor.
- Small package with thermal pad

TB67S128FTG: P-VQFN64-0909-0.50-006

Note: Please be careful about thermal conditions during using.



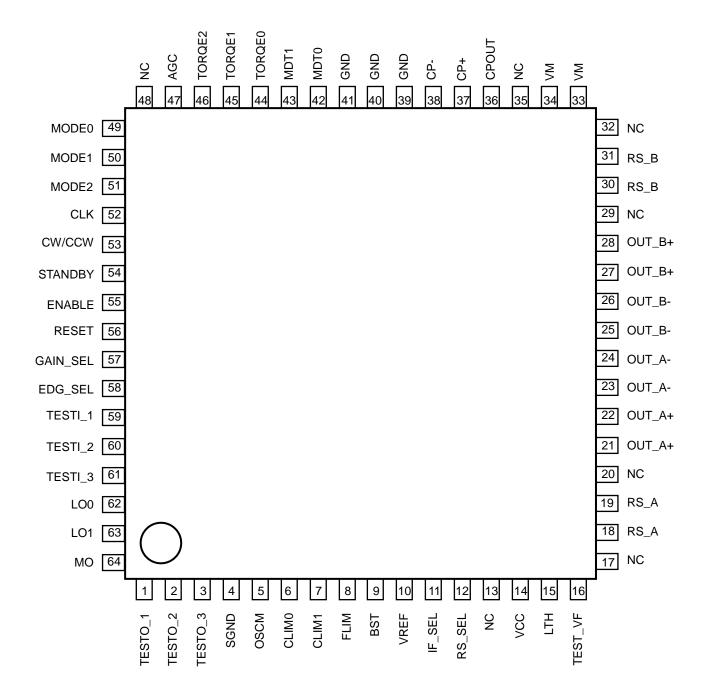
Weight: 0.229 g (typ.)



3. Pin Assignment

Pin assignment in CLK mode (IF_SEL pin = L) is shown in below figure.

<TOP View>



Note: Please solder the corner pads and the rear thermal pad of the QFN package, to the GND pattern of the PCB.



4. Pin Description

	Symbo	ol		
Pin No.	CLK mode	Serial mode	Description	
1	TESTO_1 (Note1)	TESTO_1 (Note1)	TEST OUT pin No.1	
2	TESTO_2 (Note1)	TESTO_2 (Note1)	TEST OUT pin No.2	
3	TESTO_3 (Note1)	TESTO_3 (Note1)	TEST OUT pin No.3	
4	SGND	SGND	Logic ground pin	
5	OSCM	OSCM	Internal oscillator frequency monitor and setting pin	
6	CLIM0 (Note1)	NC (Note1)	AGC current limiter setup pin No.0	
7	CLIM1 (Note1)	NC (Note1)	AGC current limiter setup pin No.1	
8	FLIM (Note1)	NC (Note1)	AGC frequency limiter setup pin	
9	BST (Note1)	NC (Note1)	AGC current boost setup pin	
10	VREF	VREF	Current threshold reference pin	
11	IF_SEL	IF_SEL	Interface select pin	
12	RS_SEL	NC (Note1)	RS mode select pin	
13	NC	NC	NC pin	
14	VCC	VCC	Internal regulator voltage monitor pin	
15	LTH (Note1)	LTH (Note1)	AGC threshold setup pin	
16	TEST_VF (Note1)	TEST_VF (Note1)	TEST monitor (3VF)	
17	NC	NC NC	NC Pin	
			Ach current sense resistor connected pin /	
18	RS_A (Note2)	RS_A (Note2)	Ach motor power ground pin	
19	RS_A (Note2)	RS_A (Note2)	Ach current sense resistor connected pin /	
19	NO_A (Note2)	NO_A (Note2)	Ach motor power ground pin	
20	NC	NC	NC pin	
21	OUT_A+ (Note2)	OUT_A+ (Note2)	Ach motor output(+) pin	
22	OUT_A+ (Note2)	OUT_A+ (Note2)	Ach motor output(+) pin	
23	OUT_A- (Note2)	OUT_A- (Note2)	Ach motor output(-) pin	
24	OUT_A- (Note2)	OUT_A- (Note2)	Ach motor output(-) pin	
25	OUT_B- (Note2)	OUT_B- (Note2)	Bch motor output(-) pin	
26	OUT_B- (Note2)	OUT_B- (Note2)	Bch motor output(-) pin	
27	OUT_B+ (Note2)	OUT_B+ (Note2)	Bch motor output(+) pin	
28	OUT_B+ (Note2)	OUT_B+ (Note2)	Bch motor output(+) pin	
29	NC	NC	NC pin	
30	RS_B (Note2)	RS_B (Note2)	Bch current sense resistor connected pin /	
			Bch motor power ground pin Bch current sense resistor connected pin /	
31	RS_B (Note2)	RS_B (Note2)	Bch motor power ground pin	
32	NC	NC	NC pin	
33	VM (Note2)	VM (Note2)	Motor power supply input pin	
34	VM (Note2)	VM (Note2)	Motor power supply input pin	
35	NC	NC	NC pin	
36	CPOUT	CPOUT	Pin for Charge pump	
37	CP+	CP+	Pin for Charge pump	
38	CP-	CP-	Pin for Charge pump	
39	GND	GND	GND	
40	GND	GND	GND	
41	GND	GND	GND	
42	MDT0	NC (Note1)	Mixed Decay/ADMD setting pin	
	MDT1	NC (Note1)	Mixed Decay/ADMD setting pin	



D'a Ma	Symbo	ol	Description	
Pin No.	CLK mode	Serial mode	Description	
44	TORQE0	NC (Note1)	Torque setting pin No.0	
45	TORQE1	NC (Note1)	Torque setting pin No.1	
46	TORQE2	NC (Note1)	Torque setting pin No.2	
47	AGC	NC (Note1)	Active Gain Control setup pin	
48	NC	NC	NC pin	
49	MODE0	NC (Note1)	Excitation setting pin No.0	
50	MODE1	NC (Note1)	Excitation setting pin No.1	
51	MODE2	NC (Note1)	Excitation setting pin No.2	
52	CLK	CLK	Step clock input pin / Serial clock input pin	
53	CW/CCW	DATA	Current direction setup pin / Data input pin in serial interface	
54	STANDBY	STANDBY	Standby pin	
55	ENABLE	LATCH	Motor output ON/OFF pin / Latch Enable input pin	
56	RESET	BANK_EN	Electrical angle initialize pin / BANK select pin	
57	GAIN_SEL	NC (Note1)	Vref Gain setting pin	
58	EDG_SEL	NC (Note1)	CLK edge setting pin	
59	TESTI_1 (Note1)	TESTI_1 (Note1)	TEST input pin No.1	
60	TESTI_2 (Note1)	TESTI_2 (Note1)	TEST input pin No.2	
61	TESTI_3 (Note1)	TESTI_3 (Note1)	TEST input pin No.3	
62	LO0	LO0	Error detection flag output pin No.0	
63	LO1	LO1	Error detection flag output pin No.1	
64	MO	NC (Note1)	Electrical angle monitor pin	

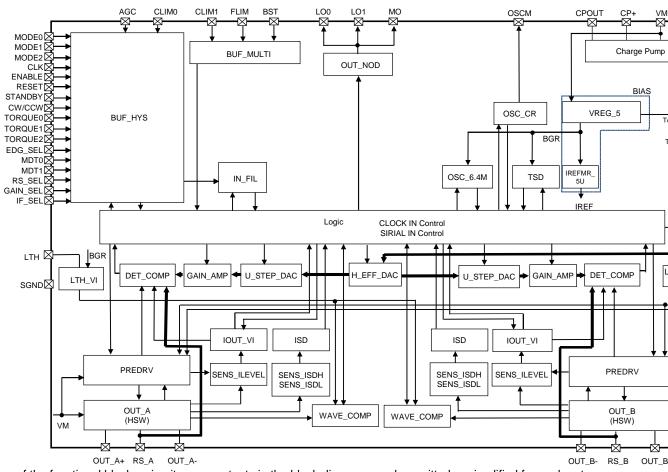
Note1: When this pin is not used, the pin should be opened or connected to Ground.

Note2: The same name pins should be connected with PCB pattern each other.

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5. Block Diagram



Note: Some of the functional blocks, circuits, or constants in the block diagram may be omitted or simplified for explanatory purpose.

Note: All the grounding wires of the TB67S128FTG should run on the solder mask on the PCB and be externally terminated at only considered for efficient heat dissipation. Careful attention should be paid to the layout of the output, VM and GND traces, to avoid supply or ground. If such a short circuit occurs, the device may be permanently damaged. Also, the utmost care should be taken device since it has power supply pins (VM, RS line, OUT line, and GND) through which a particularly large current may run. If the may occur or the device may be destroyed. The logic input pins must also be wired correctly. Otherwise, the device may be dam that is larger than the specified current. Careful attention should be paid to design patterns and mountings.



6. INPUT/OUTPUT Equivalent Circuit

Pin name	IN/OUT signal	Equivalent circuit
MODE0, 1, 2 CLK ENABLE RESET CW/CCW TORQE0, 1, 2 EDG_SEL MDT0, 1 RS_SEL GAIN_SEL IF_SEL STANDBY CLIM0 AGC	Digital Input (VIH/VIL) VIH: 2.0 V (min) to 5.5 V (max) VIL: 0 V (min) to 0.8 V (max)	Logic input pin $\begin{array}{c c} & 1 & k\Omega \\ \hline & & & & \\ \hline & & & & \\ \hline & & & & \\ \hline & & & &$
LO0, LO1 MO	Digital Output (VOH/VOL) (Pullup resistance:10 k to 100 kΩ)	Logic Output Pin
VCC VREF	VCC voltage range 4.75 V (min) 5.0 V (typ.) 5.25 V (max) VREF voltage range 0 V to 3.6 V	VCC Δ VREF Δ W
OSCM	OSCM frequency setting range 0.64 MHz (min) 1.12 MHz (typ.) 2.4 MHz (max)	OSCM A LANGE OSCM CONTRACTOR O
OUT_A+ OUT_A- OUT_B+ OUT_B- RS_A RS_B	VM power supply voltage range 6.5 V (min) to 44 V (max)	OUT_X+ OUT_X- GND RS_X X = A or B



Pin name	IN/OUT signal	Equivalent circuit
CLIM1 FLIM BST	Multi state input pin voltage Connect to VCC Connect to GND Connect to VCC with 100 k Ω pull-up resistor Connect to GND with 100 k Ω pull-down resister (Resistor accuracy should be within ± 20 %.)	VCC 100 kΩ 1 kΩ 1 kΩ 100 kΩ 100 kΩ
LTH	Connect to GND with 100 k Ω pull-down resistor (Resistance accuracy should be within ± 20 %.)	500 Ω LTH
CPOUT CP+ CP-	VM power supply voltage range 6.5 V (min) to 44 V (max) OUTPUT pin voltage 11.2 V (min) to 48.7 V (max)	CP+ OUTPUT COntrol CP- OUTPUT Control

Note: The equivalent circuit diagrams may be simplified for explanatory purposes.



7. IF Select Function

IF can be selected from CLK mode or serial mode.

IF_SEL pin input	Function
L	CLK mode
Н	Serial mode

8. Functional Description 1 (for CLK mode when IF_SEL pin = L)

8.1. CLK Function

Each up-edge of the CLK signal will shift the motor's electrical angle per step.

When EDG_SEL pin = L (Single Edge)

CLK pin input	Function
Up-edge	Shifts the electrical angle per step.
Down-edge	(State of the electrical angle does not change.)

When EDG_SEL pin = H (Double Edge)

CLK pin input	Function
Up-edge	Shifts the electrical angle per step.
Down-edge	Shifts the electrical angle per step.

8.2. ENABLE Function

The ENABLE pin controls the ON and OFF of the stepping motor outputs. Motor operation starts and stops by setting H and L to the ENABLE pin. (When ENABLE pin is set to L (OFF), all of the MOSFETs turn off and become high impedance (hereafter, Hi-Z).)

Setting the ENABLE pin to L, and avoiding the motor to operate during VM power-on and power-off (i.e., outside of the operating voltage range) is recommended. Then, switch the ENABLE pin to H after the VM reaches the target voltage and becomes stable.

ENABLE pin input	Function
L	OFF (High impedance mode, later omitted Hi-Z mode later)
Н	ON (Normal operation mode)

8.3. CW/CCW Function and the Output Pin Function (Output logic at the time of a charge start)

The CW/CCW pin controls the rotation direction of the motor. When set to H, the current of OUT_A is output first, with a phase difference of 90°. When set to L, the current of OUT_B is output first with a phase difference of 90°.

CW/CCW pin input	OUT_x+	OUT_x-
L: Counter clockwise operation (CCW)	L	Н
H: Clockwise operation (CW)	Н	L

Note: x = A or B



8.4. Step Resolution Select Function

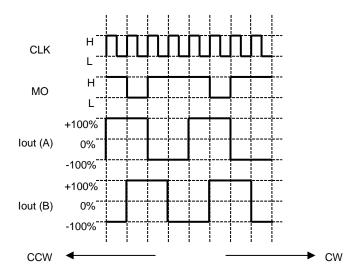
MODE~0,~MODE1,~and~MODE2~pins~control~the~step~resolution. Pin levels of MODE0, MODE1, and MODE2 can be switched during operation. The following step current depends on the electrical angle.

MODE2 pin input	MODE1 pin input	MODE0 pin input	Function
L	L	L	Full step resolution
L	L	Н	Half step resolution
L	Н	L	Quarter step resolution
L	Н	Н	1/8 step resolution
Н	L	L	1/16 step resolution
Н	L	Н	1/32 step resolution
Н	Н	L	1/64 step resolution
Н	Н	Н	1/128 step resolution

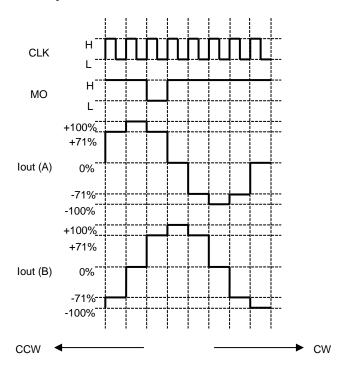


8.5. Timing Chart of Step Resolution Setting and Initial Angel

[Full step resolution]



[Half step resolution]

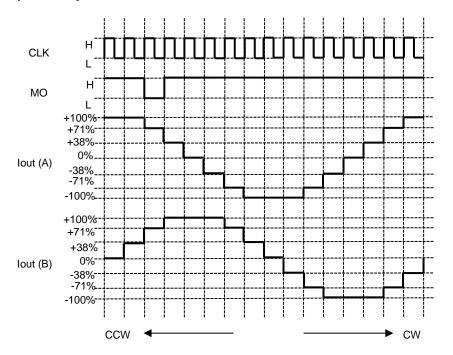


Note: MO signal is shown in the above timing chart when MO pin is connected with a pull-up resistor to VCC.

Note: Timing charts may be simplified for explanatory purpose.

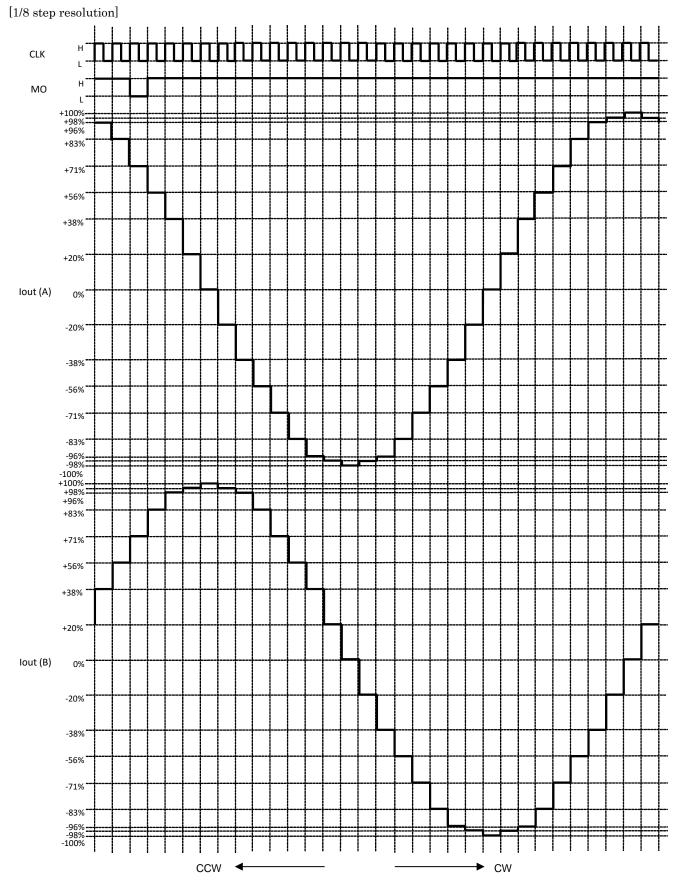


[Quarter step resolution]



Note: MO signal is shown in the above timing chart when MO pin is connected with a pull-up resistor to VCC. Note: Timing charts may be simplified for explanatory purpose.

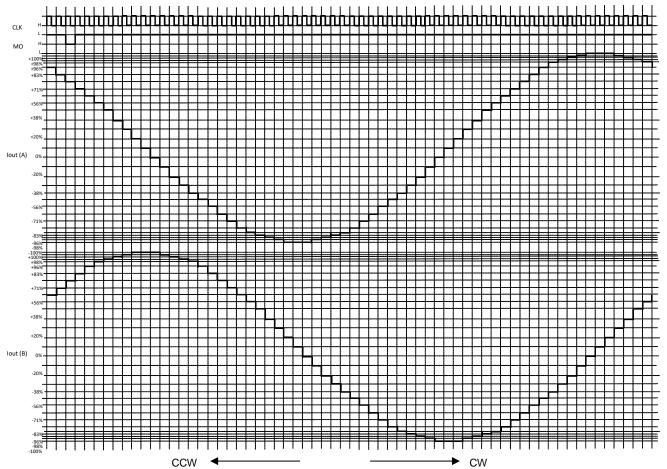




Note: MO signal is shown in the above timing chart when MO pin is connected with a pull-up resistor to VCC. Note: Timing charts may be simplified for explanatory purpose.

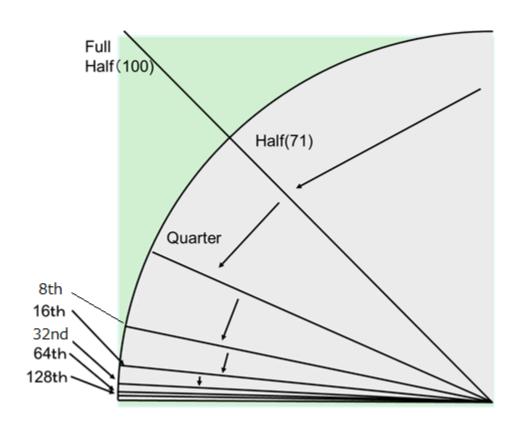


[1/16 step resolution]



Note: MO signal is shown in the above timing chart when MO pin is connected with a pull-up resistor to VCC.

Note: Timing charts may be simplified for explanatory purpose.





8.6. Step Setting and Current Percentage

Current (%)	Full	Half	Quarter	1/8	1/16	1/32	1/64	1/128
100%	Available	Available	Available	Available	Available	Available	Available	Available
99%					Available	Available	Available	Available
98%				Available	Available	Available	Available	Available
97%					Available	Available	Available	Available
96%				Available	Available	Available	Available	Available
95%							Available	Available
94%						Available	Available	Available
93%							Available	Available
92%						Available	Available	Available
91%							Available	Available
90%					Available	Available	Available	Available
89%							Available	Available
88%						Available	Available	Available
87%							Available	Available
86%						Available	Available	Available
85%								Available
84%							Available	Available
83%				Available	Available	Available	Available	Available
82%							Available	Available
81%								Available
80%						Available	Available	Available
79%							Available	Available
78%							7.174.114.115	Available
77%					Available	Available	Available	Available
76%					7174114510	7 (Valiable	Available	Available
75%							7174114515	Available
74%						Available	Available	Available
73%						/ (Valiable	7 (Valiable	Available
72%							Available	Available
71%		Available	Available	Available	Available	Available	Available	Available
70%		Available	Available	Available	Available	Available	Available	Available
69%							Available	Available
							Available	
68% 67%						Available	Available	Available Available
						Available	Available	
66% 65%							Avoilable	Available
							Available	Available
64%					Available	Available	Available	Available
63%					Available	Available	Available	Available
62%							Available	Available
61%						A !! - !- ! -	۸. مها ا - ا - ا	Available
60%						Available	Available	Available
59%							۸. مها ا - ا - ا	Available
58%							Available	Available
57%				A	A	A	A	Available
56%				Available	Available	Available	Available	Available
55%								Available
53%							Available	Available
52%								Available
51%						Available	Available	Available
50%								Available
49%							Available	Available
48%								Available
47%					Available	Available	Available	Available
46%								Available



Current (%)	Full	Half	Quarter	1/8	1/16	1/32	1/64	1/128
45%							Available	Available
44%								Available
43%						Available	Available	Available
42%								Available
41%							Available	Available
39%								Available
38%			Available	Available	Available	Available	Available	Available
37%								Available
36%							Available	Available
35%								Available
34%						Available	Available	Available
33%								Available
31%							Available	Available
30%								Available
29%					Available	Available	Available	Available
28%								Available
27%							Available	Available
25%						Available		Available
24%							Available	Available
23%								Available
22%							Available	Available
21%								Available
20%				Available	Available	Available	Available	Available
18%								Available
17%							Available	Available
16%								Available
15%						Available	Available	Available
13%								Available
12%							Available	Available
11%								Available
10%					Available	Available	Available	Available
9%								Available
7%							Available	Available
6%								Available
5%						Available	Available	Available
4%								Available
2%							Available	Available
1%								Available
0%		Available						



8.7. Step Resolution and Set Current

STEP	1/1	28	1/	64	1/	32	1/	16	1.	/8	1,	/4	1.	/2	F	ull
_	Ach	Bch	Ach	Bch												
θ0	(%) 100	(%) 0	(%)	(%)												
θ1	100	1														
θ2	100	2	100	2												
θ3	100	4														
θ4	100	5	100	5	100	5										
θ5	100	6														
θ6	100	7	100	7												
θ7	100	9														
θ8	100	10	100	10	100	10	100	10								
09	99	11														
θ10	99	12	99	12												
θ11	99	13														
θ12	99	15	99	15	99	15										
θ13	99	16														
θ14	99	17	99	17												
θ15	98	18														
θ16	98	20	98	20	98	20	98	20	98	20						
θ17	98	21														
θ18	98	22	98	22												
θ19	97	23														
θ20	97	24	97	24	97	24										
θ21	97	25														
θ22	96	27	96	27												
θ23	96	28														
θ24	96	29	96	29	96	29	96	29								
θ25	95	30														
θ26	95	31	95	31												
θ27	95	33														
θ28	94	34	94	34	94	34										
θ29	94	35														
θ30	93	36	93	36												
θ31	93	37														
θ32	92	38	92	38	92	38	92	38	92	38	92	38				
θ33	92	39														
θ34	91	41	91	41												



STEP	1/1	28	1/	64	1/	32	1/	16	1.	/8	1,	/4	1.	/2	F	ull
	Ach	Bch	Ach	Bch	Ach	Bch	Ach	Bch	Ach	Bch	Ach	Bch	Ach	Bch	Ach	Bch
θ35	(%)	(%)	(%)	(%)	(%)	(%)	(%)	(%)	(%)	(%)	(%)	(%)	(%)	(%)	(%)	(%)
	91	42	00	40	00	40										
θ36	90	43	90	43	90	43										
θ37	90	44														
θ38	89	45	89	45												
θ39	89	46														
θ40	88	47	88	47	88	47	88	47								
θ41	88	48														
θ42	87	49	87	49												
θ43	86	50														
θ44	86	51	86	51	86	51										
θ45	85	52														
θ46	84	53	84	53												
θ47	84	55														
θ48	83	56	83	56	83	56	83	56	83	56						
θ49	82	57														
θ50	82	58	82	58												
θ51	81	59														
θ52	80	60	80	60	80	60										
θ53	80	61														
θ54	79	62	79	62												
θ55	78	62														
θ56	77	63	77	63	77	63	77	63								
θ57	77	64														
θ58	76	65	76	65												
θ59	75	66														
960	74	67	74	67	74	67										
θ61	73	68														
θ62	72	69	72	69												
θ63	72	70														
θ64	71	71	71	71	71	71	71	71	71	71	71	71	71	71	100	100
θ65	70	72	ļ	ļ	ļ · ·		' '	ļ	· ·	' '	ļ · ·	ļ · ·	' '	' '	''	
966	69	72	69	72												
θ67	68	73	03	12												
968	67	73	67	74	67	74										
969			07	74	07	74										
-	66	75	05	70												
θ70	65	76	65	76												



STEP	1/1	28	1/	64	1/-	32	1/	16	1,	/8	1,	/4	1,	/2	F	ull
_	Ach	Bch	Ach	Bch	Ach	Bch	Ach	Bch	Ach	Bch	Ach	Bch	Ach	Bch	Ach	Bch
θ71	(%) 64	(%) 77	(%)	(%)	(%)	(%)	(%)	(%)	(%)	(%)	(%)	(%)	(%)	(%)	(%)	(%)
θ72	63	77	63	77	63	77	63	77								
θ73	62	78														
θ74	62	79	62	79												
θ75	61	80														
θ76	60	80	60	80	60	80										
θ77	59	81														
θ78	58	82	58	82												
θ79	57	82														
θ80	56	83	56	83	56	83	56	83	56	83						
θ81	55	84														
θ82	53	84	53	84												
θ83	52	85														
θ84	51	86	51	86	51	86										
θ85	50	86														
θ86	49	87	49	87												
θ87	48	88														
θ88	47	88	47	88	47	88	47	88								
θ89	46	89														
θ90	45	89	45	89												
θ91	44	90														
θ92	43	90	43	90	43	90										
θ93	42	91														
θ94	41	91	41	91												
θ95	39	92														
θ96	38	92	38	92	38	92	38	92	38	92	38	92				
θ97	37	93														
θ98	36	93	36	93												
θ99	35	94														
θ100	34	94	34	94	34	94										
θ101	33	95														
θ102	31	95	31	95												
θ103	30	95														
θ104	29	96	29	96	29	96	29	96								
θ105	28	96														
θ106	27	96	27	96												

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STEP	1/1	28	1/	64	1/:	32	1/	16	1,	/8	1,	/4	1,	/2	F	ull
_	Ach	Bch	Ach	Bch	Ach	Bch	Ach	Bch	Ach	Bch	Ach	Bch	Ach	Bch	Ach	Bch
θ107	(%) 25	(%) 97	(%)	(%)	(%)	(%)	(%)	(%)	(%)	(%)	(%)	(%)	(%)	(%)	(%)	(%)
θ108	24	97	24	97	24	97										
θ109	23	97	24	31	24	31										
			00	00												
θ110	22	98	22	98												
θ111	21	98														
θ112	20	98	20	98	20	98	20	98	20	98						
θ113	18	98														
θ114	17	99	17	99												
θ115	16	99														
θ116	15	99	15	99	15	99										
θ117	13	99														
θ118	12	99	12	99												
θ119	11	99														
θ120	10	100	10	100	10	100	10	100								
θ121	9	100														
θ122	7	100	7	100												
θ123	6	100														
θ124	5	100	5	100	5	100										
θ125	4	100														
θ126	2	100	2	100												
θ127	1	100														
θ128	0	100	0	100	0	100	0	100	0	100	0	100	0	100		
0120	U	100	U	100	U	100	U	100	U	100	U	100	U	100		



8.8. RESET Function

The RESET pin initializes the internal electrical angle.

RESET pin input	Function
L	Normal operation mode
Н	Sets the electrical angle to the initial condition.

Note: Digital filter of 0.625 µs (±20 %) is implemented to the RESET pin.

The current for each channel (while RESET pin is applied) is shown in the table below. MO pin will show L at this time.

Step resolution setting	Ach current setting	Bch current setting	Default electrical angle
Full step	100%	100%	45°
Half step	71%	71%	45°
Quarter step	71%	71%	45°
1/8 step	71%	71%	45°
1/16 step	71%	71%	45°
1/32 step	71%	71%	45°
1/64 step	71%	71%	45°
1/128 step	71%	71%	45°

8.9. Torque Function

By using this pin it is possible to switch the motor torque setting.

TORQE2 pin input	TORQE1 pin input	TORQE0 pin input	Function
L	L	L	Set torque: 100%
L	L	Н	Set torque: 85%
L	Н	L	Set torque: 70%
L	Н	Н	Set torque: 60%
Н	L	L	Set torque: 50%
Н	L	Н	Set torque: 40%
Н	Н	L	Set torque: 25%
Н	Н	Н	Set torque: 10%



8.10. CLK Edge Function

CLK edge function can select the CLK signal's rising edge or the CLK edge's dual (up and down).

EDG_SEL pin input	Function
L	Single edge (Only Up Edge of CLK Signal)
Н	Dual edge (Up and Down edge)

8.11. RS Function

RS function can select either ACDS mode or external sense RS resistor mode.

RS_SEL pin input	Function
L	ACDS (RS resistor less) mode
Н	External sense RS resistor mode

Note: PCB board should be designed according to RS Function. When using ACDS mode, RS $_x$ pins should be connected to GND. When using External sense RS resistor mode, the sense resistor should be connected between RS $_x$ pin and GND. (x = A or B)

8.12. Gain Function

Gain function can change Vref(gain). Vref(gain) can be selected either 1/5 or 1/10.

GAIN_SEL pin input	Function
L	Set Vref(gain) to 1/5
Н	Set Vref(gain) to 1/10

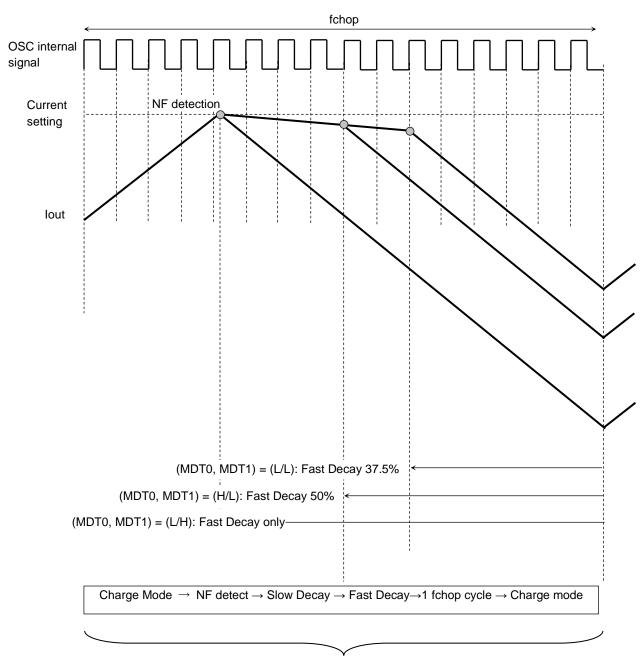


8.13. Selectable Mixed Decay Function

The Selectable Mixed Decay can adjust the current regeneration amount during the period of current regeneration (Decay) using pins.

Though the Mixed Decay is determined by controlling 2 different types of decay (Fast Decay and Slow Decay), this function enables the user to select the ratio of the Mixed Decay using MDT0 and MDT1 pin. (2bit, 4 function)

MDT1 pin input	MDT0 pin input	Function
L	L	Fast Decay: 37.5% (Fast Decay = OSCM x 6)
L	Н	Fast Decay: 50% (Fast Decay = OSCM x 8)
Н	L	Fast Decay only
Н	Н	ADMD

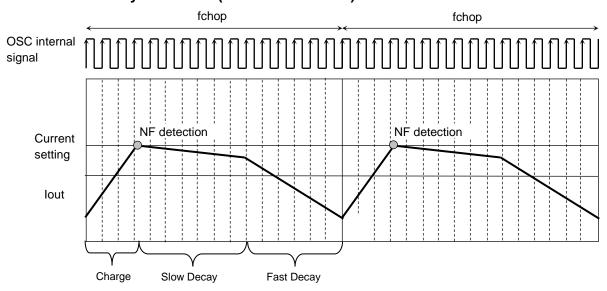


1 fchop cycle: OSCM x 16clock

Note: Timing charts may be simplified for explanatory purpose.

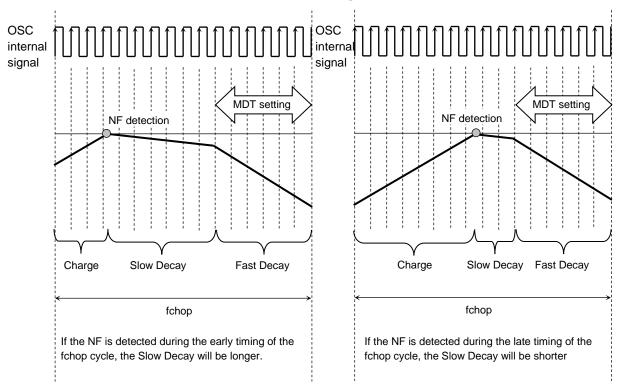


8.13.1. Mixed Decay Waveform (Current Waveform)



Note: Timing charts may be simplified for explanatory purpose.

8.13.2. Constant Current PWM Function and Timings



The Charge period is determined by the operating status.

Therefore, the NF detect timing with in the chopping cycle will change. If NF is detected in the early period of the fchop cycle, the Slow Decay will be longer. If NF is detected in the late period of the fchop cycle, the Slow Decay will be shorter, as shown above.

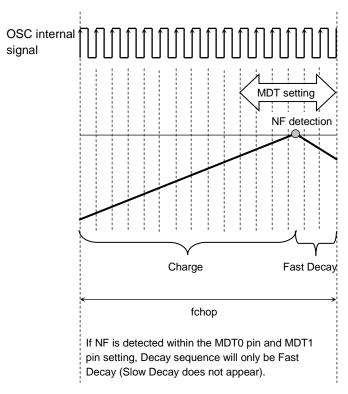
Note: The chopping cycle is determined as: fchop - (Charge + Fast decay) = Slow Decay

(Fast Decay ratio can be changed by MDT0 pin and MDT1 pin setting.)

Note: Timing charts may be simplified for explanatory purpose.



8.13.3. Constant Current PWM Function and Timing

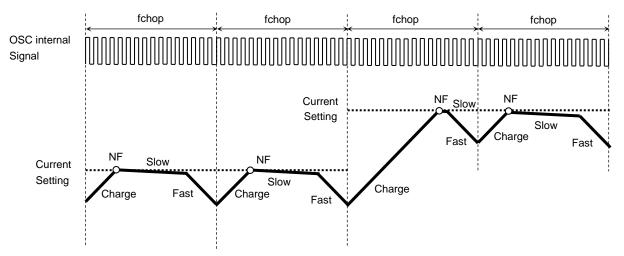


Note: Timing charts may be simplified for explanatory purpose.



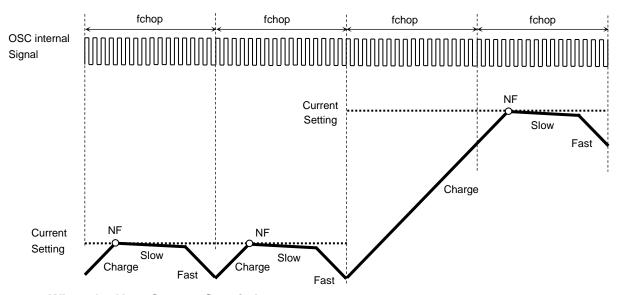
8.13.4. Mixed Decay current waveform

• When the next current step is higher:

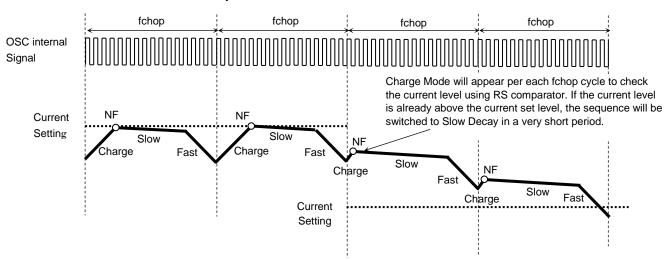


When Charge Period is More Than 1 fchop Cycle:

When the Charge period is longer than fchop cycle, the Charge period extends until the motor current reaches the NF threshold. Once the current reaches the next current step, then the sequence goes on to decay mode.



When the Next Current Step is Lower:



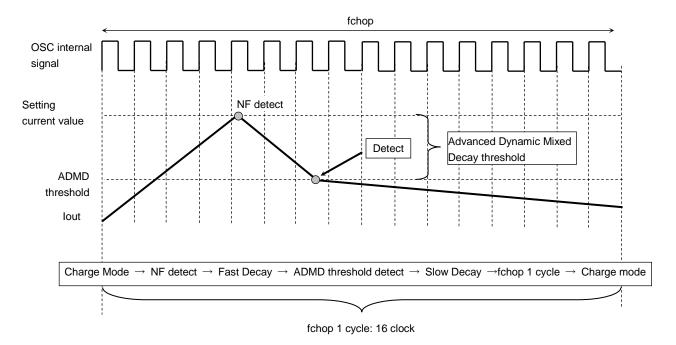
Note: Timing charts may be simplified for explanatory purpose.



8.13.5. ADMD (Advanced Dynamic Mixed Decay) Constant Current Control (MDT0 pin = H, MDT1 pin = H)

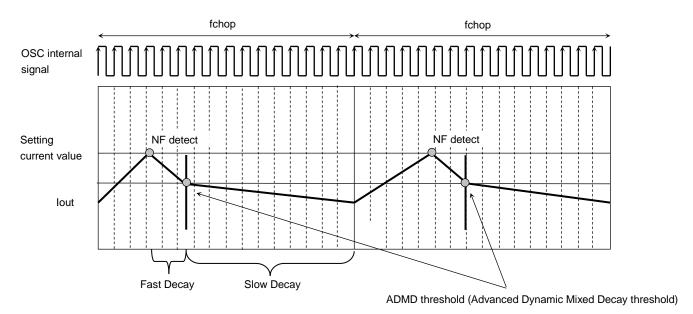
The TB67S128FTG supports the Advanced Dynamic Mixed Decay (ADMD) which monitors both charge and discharge current during constant current PWM.

The basic sequence of the ADMD is as shown below.



Note: Timing charts may be simplified for explanatory purpose.

8.13.5.1. Auto Decay Mode Current Waveform 1

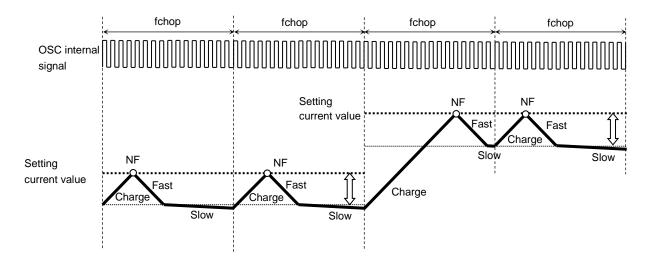


Note: Timing charts may be simplified for explanatory purpose.



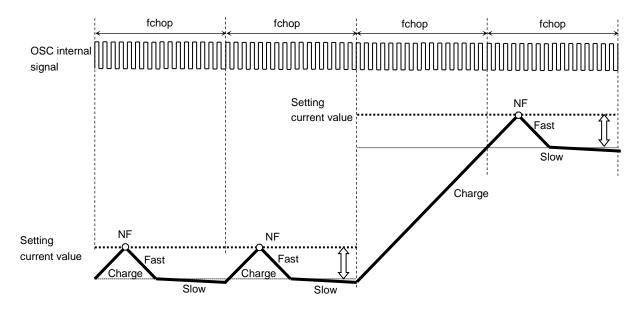
8.13.5.2. Auto Decay Mode Current Waveform 2

• When the Next Current Step is Higher:



When Charge Period is More Than 1 fchop Cycle:

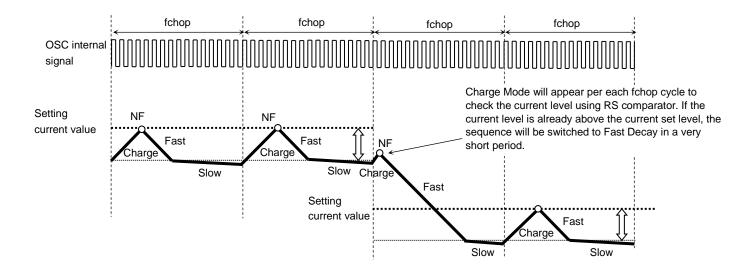
When the Charge period is longer than fchop cycle, the Charge period will be extended until the motor current reaches the NF threshold. Once the current reaches the next current step, then the sequence will go on to decay mode.



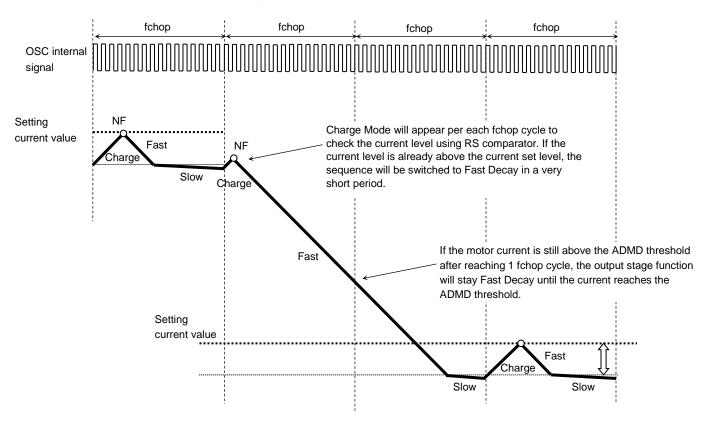
Note: Timing charts may be simplified for explanatory purpose.



• When the Next Current Step is Lower:



 When the Fast Continues Past 1 fchop Cycle (the motor current not reaching the ADMD threshold during 1 fchop cycle)



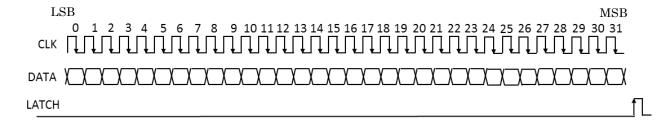
Note: Timing charts may be simplified for explanatory purpose.



9. Functional Description 2 (for Serial mode when IF_SEL pin = H)

When IF_SEL pin = H, the interface is serial mode. It performs setting and motor control in the following 32-bit format.

When BANK_EN pin is L, initial setting is performed. When the BANK_EN pin is H, the motor is controlled. For the motor control, each current value is set in the serial setting, and the output is updated to the set current value at the timing of the LATCH signal.



BANK_EN = L: Initial setting

1	D0	D1	D2	D3	D4	D5	D6	D7	D8	D9	D10	D11	D12	D13	D14	D15
	טט	וט	DZ	D3	D4	Do	סט	וט	Do	D9	טוט	ווע	DIZ	DIS	D14	כוע
	0	0	AGC	CLIM 0	CLIM 1	CLIM 2	FLIM 0	FLIM 1	BST0	BST1	0	0	RS_ SEL	GAIN _SEL	0	0

	D16	D17	D18	D19	D20	D21	D22	D23	D24	D25	D26	D27	D28	D29	D30	D31
Ī	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Note: The data which has a same name as a pin name in CLK mode performs as same as the pin in CLK mode.

BANK_EN = H: Motor controlling

D0	D1	D2	D3	D4	D5	D6	D7	D8	D9	D10	D11	D12	D13	D14	D15
0	0	TOR QE0	TOR QE1	TOR QE2	0	MDT _A0	MDT _A1	PHA	CA0	CA1	CA2	CA3	CA4	CA5	CA6

I	D16	D17	D18	D19	D20	D21	D22	D23	D24	D25	D26	D27	D28	D29	D30	D31
I	CA7	CA8	CA9	MDT _B0	MDT _B1	PHB	CB0	CB1	CB2	CB3	CB4	CB5	CB6	CB7	CB8	CB9

Note: Every issuing a command, the current setting transfers by one step.



9.1. Registers When BANK_EN pin = H

The registers when $BANK_EN$ pin = H are shown below.

9.1.1. PHx (x = A and B)

The polality of the output current can be selected by PHx register for each channels.

PHx register setting	Function
L	Setting the direction of the output current to minus
Н	Setting the direction of the output current to plus

9.1.2. Cx0 to Cx9 (x = A or B)

The output of each channel's DAC for current limitation can be set by Cx0 to Cx9. The relation between Setting DAC and the output current (Iout) are shown below.

A) External Sense Resistor mode

lout (max) = Vref(gain)
$$\times \frac{\text{Vref (V)}}{\text{RS (}\Omega\text{)}} \times \frac{\text{Cx}[9:0]}{1023} \times \text{Setting torque by the torque function (%)}$$
 (x = A or B)

B) RS Resistor Less Mode (ACDS)

$$\label{eq:Vref(gain)} Vref(gain) = \frac{1}{5} \mbox{ (typ.) (when GAIN_SEL pin = L)}$$

$$\mbox{Iout (max)} = 1.56 \mbox{ \times Vref (V)$ \times $\frac{Cx[9:0]}{1023}$ \times Setting torque by the torque function (%)}$$

$$\mbox{Vref(gain)} = \frac{1}{10} \mbox{ (typ.) (when GAIN_SEL pin= H)}$$

$$\mbox{Iout (max)} = 0.78 \mbox{ \times Vref (V)$ \times $\frac{Cx[9:0]}{1023}$ \times Setting torque by the torque function (%)}$$

$$\mbox{($x = A$ or B)}$$

9.1.3. TORQE[0:2]

The motor torque can be set by TORQE[0:2].

TORQE2	TORQE2 TORQE1		Function
0	0	0	Set torque:100%
0	0	1	Set torque: 85%
0	1	0	Set torque: 70%
0	1	1	Set torque: 60%
1	0	0	Set torque: 50%
1	0	1	Set torque: 40%
1	1	0	Set torque: 25%
1	1	1	Set torque: 10%



9.1.4. $MDT_x[0:1]$ (x = A or B)

The Selectable Mixed Decay can adjust the current regeneration amount during the period of current regeneration (Decay).

MDT_x1	MDT_x0	Function			
0	0	Fast Decay: 37.5% (Fast Decay = OSCM × 6)			
0	1	Fast Decay: 50% (Fast Decay = OSCM x 8)			
1	0	Fast Decay only			
1 1		ADMD			

9.1.5. RS_SEL

RS_SEL can select either ACDS mode or external sense RS resistor mode.

RS_SEL	Function
L	ACDS (RS resistor less) mode
Н	External sense RS resistor mode

Note:

PCB board should be designed according to RS Function. When using ACDS mode, RS $_x$ pins should be connected to GND. When using External sense RS resistor mode, the sense resistor should be connected between RS $_x$ pin and GND. (x = A or B)

9.1.6. GAIN_SEL

Vref(gain) can be selected either 1/5 or 1/10.

GAIN_SEL	Function				
L	Vref(gain) = 1/5				
Н	Vref(gain) = 1/10				



9.2. Serial setting example when driving a motor

Serial setting example for motor operation is shown below.

- Set the BANK_EN pin L. Initial setting for AGC, etc. is performed under this condition. Then, set the BANK_EN pin H and configure the motor control to turn on the output transistors. Transmit the 1st to 4th commands repeatedly by keeping the BANK_EN pin level H. The motor operates 2. 3. with full step resolution.

1st co	ommand														
D0	D1	D2	D3	D4	D5	D6	D7	D8	D9	D10	D11	D12	D13	D14	D15
0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1
D16	D17	D18	D19	D20	D21	D22	D23	D24	D25	D26	D27	D28	D29	D30	D31
1	1	1	0	0	1	1	1	1	1	1	1	1	1	1	1
2nd c	omman	d													
D0	D1	D2	D3	D4	D5	D6	D7	D8	D9	D10	D11	D12	D13	D14	D15
0	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1
		1	ı	ı	1	ı	ı	ı	ı	1	ı	1	ı		
D16	D17	D18	D19	D20	D21	D22	D23	D24	D25	D26	D27	D28	D29	D30	D31
1	1	1	0	0	1	1	1	1	1	1	1	1	1	1	1
3rd co	ommano	l													
D0	D1	D2	D3	D4	D5	D6	D7	D8	D9	D10	D11	D12	D13	D14	D15
0	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1
	1														
D16	D17	D18	D19	D20	D21	D22	D23	D24	D25	D26	D27	D28	D29	D30	D31
1	1	1	0	0	0	1	1	1	1	1	1	1	1	1	1
4th co	ommand														
D0	D1	D2	D3	D4	D5	D6	D7	D8	D9	D10	D11	D12	D13	D14	D15
0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1
	1									1		1			
D16	D17	D18	D19	D20	D21	D22	D23	D24	D25	D26	D27	D28	D29	D30	D31
1	1	1	0	0	0	1	1	1	1	1	1	1	1	1	1

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10. Stepping Motor Application Features (Anti-stall, RS resistor less PWM)

10.1. Active Gain Control (Anti-stall) Function

AGC pin will set the Active Gain Control to turn on or off. When this pin is set to H, the AGC is turned on, and when this pin is set to L, the AGC is turned off.

When the AGC is ON, the motor current is equal or more than the value by setting the VREF pin. The TB67S128FTG reduces gradually the motor current depending on the load torque.

When the AGC is OFF, the motor current is the value by setting the VREF pin.

AGC pin input	Function
L	AGC: OFF
Н	AGC: ON

Note: Please do not change the AGC pin when the TB67S128FTG is powered on.

Note: There is a built-in digital filter of 0.625 µs (±20%) for AGC pin.

Serial setting is shown below.

AGC bit	Function
0	AGC: OFF
1	AGC: ON

10.2. CLIM (AGC Bottom Current Limit) Function

When AGC is active, the motor current is reduced according to the load torque. The CLIM0 and CLIM1 pins set the lower threshold of the current threshold for AGC.

The CLIM0 pin is a 2 stated logic input, and the CLIM1 pin is a 4 stated logic input.

CLIM0 pin input	CLIM1 pin input	Function				
	VCC short	AGC bottom current limit: lout × 60%				
	VCC - 100 kΩ pull-up	AGC bottom current limit: lout x 55%				
L	GND - 100 kΩ pull-down	AGC bottom current limit: lout × 50%				
	GND short	AGC bottom current limit: lout x 45%				
	VCC short	AGC bottom current limit: lout × 80%				
ш	VCC - 100 kΩ pull-up	AGC bottom current limit: lout × 75%				
Н	GND - 100 kΩ pull-down	AGC bottom current limit: lout x 70%				
	GND short	AGC bottom current limit: lout × 65%				

Note: Pull-up and pull-down resistor tolerance should be kept within ± 20 %.

Note: There is a built-in digital filter of 0.625 $\mu s(\pm 20\%)$ for CLIM0 and CLIM1 pin.

Serial setting is shown below.

CLIM2 bit	CLIM1 bit	CLIM0 bit	Function
	0	0	AGC bottom current limit: lout × 45%
0	1	1	AGC bottom current limit: lout × 50%
U		0	AGC bottom current limit: lout × 55%
		1	AGC bottom current limit: lout × 60%
	0	0	AGC bottom current limit: lout × 65%
1	U	1	AGC bottom current limit: lout x 70%
'	1	0	AGC bottom current limit: lout × 75%
		1	AGC bottom current limit: lout x 80%



10.3. BOOST (Current Boost) Function

When AGC is active, the motor current is reduced according to the load torque. In this state, the BST pin sets the current boost level when the load torque increases. The BST pin is a 4 stated logic input pin.

BST pin input	Function	
VCC short	Takes 5 steps maximum (Design value)	
VCC - 100 kΩ pull-up	Takes 7 steps maximum (Design value)	
GND - 100 kΩ pull-down	Takes 9 steps maximum (Design value)	
GND short	Takes 11 steps maximum (Design value)	

Note: Pull-up and pull-down resistor tolerance should be kept within ±20 %.

Note: There is a built-in digital filter of 0.625 µs(±20%) for BST pin.

Note: Current boost step is largest when BST pin is tied to VCC, and smallest when tied to the GND.

Serial setting is shown below.

BST1 bit	BST0 bit	Function
0	0	Takes 11 steps maximum (Design value)
U	1	Takes 9 steps maximum (Design value)
1 -	0	Takes 7 steps maximum (Design value)
	1	Takes 5 steps maximum (Design value)

10.4. FLIM (AGC Frequency limit) function

The FLIM pin will set the lower frequency limit for the AGC to be active. The FLIM function is effective when the AGC is used to avoid the motor resonance frequency during ramp up.

The FLIM pin is a 4 stated logic input.

FLIM pin input	Function
VCC short	Frequency limit: ON, AGC is invalid when fCLK is below 675 Hz
VCC - 100 kΩ pull-up	Frequency limit: ON, AGC is invalid when fCLK is below 450 Hz
GND - 100 kΩ pull-down	Frequency limit: ON, AGC is invalid when fCLK is below 225 Hz
GND short	FLIM: OFF

Note: Pull-up and pull-down resistor tolerance should be kept within ±20 %.

Note: There is a built-in digital filter of 0.625 $\mu s(\pm 20\%)$ for FLIM pin.

The frequency (fCLK) shown above is for full step resolution. The frequency limit threshold will depend on the step resolution setting.

FLIM pin input	1/1	1/2	1/4	1/8	1/16	1/32	1/64	1/128
VCC short	675 Hz	1.35 kHz	2.7 kHz	5.4 kHz	10.8 kHz	21.6 kHz	43.2 kHz	86.4 kHz
VCC - 100 kΩ pull-up	450 Hz	900 Hz	1.8 kHz	3.6 kHz	7.2 kHz	14.4 kHz	28.8 kHz	57.6 kHz
GND - 100 kΩ pull-down	225 Hz	450 Hz	900 Hz	1.8 kHz	3.6 kHz	7.2 kHz	14.4 kHz	28.8 kHz
GND short				FLIM	: OFF			

Note: Pull-up and pull-down resistor tolerance should be kept within ±20 %.



Serial setting is shown below.

FLIM1 bit	FLIM0 bit	Function
0	0	FLIM: OFF
	1	Frequency limit: ON, AGC is invalid when fCLK is below 225 Hz
1	0	Frequency limit: ON, AGC is invalid when fCLK is below 450 Hz
	1	Frequency limit: ON, AGC is invalid when fCLK is below 675 Hz

Note: The fCLK in serial mode will depend on the step of output current which changes with Cx[0:9] and PHx setup

10.5. LTH (AGC detection threshold) function

The LTH pin sets the AGC detection threshold. Connect a 100 k Ω pull-down resistor to GND.

LTH	Function
GND - 100 kΩ pull-down	Sensitivity of the Anti-stall detection standard setting

Note: Pull-down resistor tolerance should be kept within ±20 %.



11. Common Function (When CLK Mode and Serial Mode)

11.1. LO (Error detect flag output) Function

When an error detection function performs, the LO function outputs an error detection as a signal from LO0 and LO1 pins to the outside of TB67S128FTG.

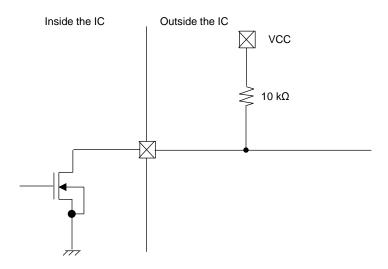
The LO0 and LO1 pins are open-drain output pins. The LO0 and LO1 pins need to be pulled up to VCC level via 10 k to 100 $k\Omega$ resistor.

During regular operation, the level of LO0 and LO1 pins will stay Hi-Z (the internal MOSFET is OFF, the level of these pins are VCC level).

When the thermal shutdown (TSD), Over current (ISD), or motor load open (OPD) occurs, the LO0 and/or LO1 pins will become L (the internal MOSFET is ON).

When the error detection is released by reasserting the VM power supply or setting the device to STANDBY mode, the LO0 and LO1 pins show "normal status".

Leave the LO0 and LO1 pins open when not using these functions.



Note: This figure may be simplified for explanatory purpose.

LO0 pin output	LO1 pin output	Function
Hi-Z	Hi-Z	Normal status (Normal operation)
Hi-Z	L	Detected motor load open (OPD)
L	Hi-Z	Detected over current (ISD)
L	L	Detected thermal shutdown (TSD)

11.2. STANDBY Function

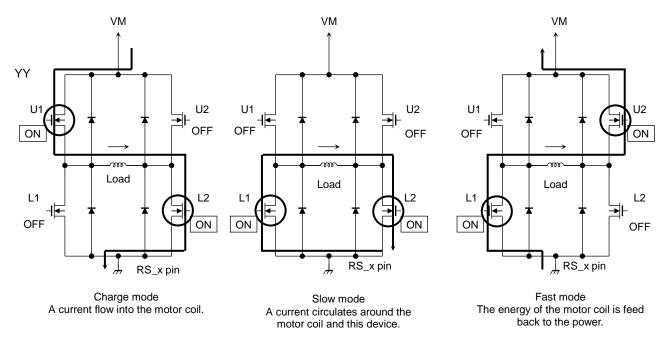
It is possible to switch to Standby mode by switching this pin

STANDBY pin input	Function
L	Standby mode
Н	Normal operation

Note: In STANDBY pin = L, an internal oscillating circuit and a motor output part are stopped. At this time, the motor cannot be driven.



12. Output Transistor Function Mode



Note: x = A or B

Note: The equivalent circuit diagrams may be simplified or some parts of them may be omitted for explanatory purposes.

Output transistor function

MODE	U1	U2	L1	L2
CHARGE	ON	OFF	OFF	ON
SLOW	OFF	OFF	ON	ON
FAST	OFF	ON	ON	OFF

Note: This table shows an example of when the current flows as indicated by the arrows in the figures shown above. If the current flows in the opposite direction, refer to the following table.

MODE	U1	U2	L1	L2
CHARGE	OFF	ON	ON	OFF
SLOW	OFF	OFF	ON	ON
FAST	ON	OFF	OFF	ON

This IC controls the motor current to be constant by changing 3 modes listed above automatically.



13. Calculation of the Predefined Output Current

13.1. External Sense Resistor mode

For PWM constant-current control, this IC uses a clock generated by the OSCM oscillator.

The peak output current (Setting current value) can be set via the current-sensing resistor (RS) and the reference voltage (Vref), as follows:

Iout (max) = Vref(gain)
$$\times \frac{\text{Vref (V)}}{\text{RS (}\Omega\text{)}}$$

Note: When GAIN_SEL pin = L, $Vref(gain) = \frac{1}{5}$ (typ.). And When GAIN_SEL pin = H, $Vref(gain) = \frac{1}{10}$ (typ.).

For example:

When Vref = 3.0 (V), RS = 0.22 Ω , Torque = 100% and Vref(gain) = $\frac{1}{5}$ (typ.) (When GAIN_SEL pin = L), motor constant current (Setting current value) will be calculated by the following expressions.

Iout (max) =
$$\frac{1}{5} \times \frac{3 \text{ (V)}}{0.22 \text{ (}\Omega\text{)}} = 2.73 \text{ A}$$

13.2. RS Resistor Less Mode (ACDS)

The Iout (max) will be calculated by the following expressions.

When
$$Vref(gain) = \frac{1}{5}$$
 (typ.) (GAIN_SEL = L)
 $Iout (max) = 1.56 \times Vref (V)$

When
$$Vref(gain) = \frac{1}{10}$$
 (typ.) (GAIN_SEL = H)
 $Iout (max) = 0.78 \times Vref (V)$

14. Calculation of the OSCM Oscillation Frequency (chopper reference frequency)

An approximation of the OSCM oscillation frequency (fOSCM) and chopper frequency (fchop) can be calculated by the following expressions.

$$fOSCM = \frac{1}{0.56 \times \{COSC \times (ROSC + 500)\}}$$
$$fchop = \frac{fOSCM}{16}$$

Note: COSC: Capacitor connected to OSCM pin, ROSC: Resistor connected to OSCM pin

For example:

When COSC = 270 pF and $ROSC = 5.1 \text{ k}\Omega$, fOSCM frequency will be calculated by following expressions.

$$fOSCM = \frac{1}{0.56 \times \{270 \text{ pF} \times (5.1 \text{ k}\Omega + 500)\}} \approx 1.2 \text{ (MHz)(typ.)}$$

$$fchop = \frac{fOSCM}{16} = \frac{1.2 \text{ (MHz)}}{16} \approx 75 \text{ (kHz)}$$

If chopping frequency is raised, Rippl of current will become small and wave-like reproducibility will improve. However, the gate loss inside IC goes up and generation of heat becomes large.

By lowering chopping frequency, reduction in generation of heat is expectable. However, Rippl of current may become large.

It is a standard about 70 kHz. A setup in the range of 50k to 100 kHz is recommended.



15. Absolute Maximum Ratings (Ta = 25°C)

Characteristics	Symbol	Rating	Unit	Remarks
Motor output voltage	Vout	50	V	_
Motor power supply (non active)	\ /N /	50	V	STANDBY pin = L
Motor power supply (active)	VM	-0.4 to 44	V	STANDBY pin = H
Motor output current	lout	5.0	Α	(Note1)
	VCPP	VM ± 6 V	V	_
Charge pump voltage	VCPM	VM ± 6 V	V	_
	VCPO	50	V	_
Internal Logic power supply	VCC	6.0	V	_
Lania inputualtana	VIN(H)	6.0	V	_
Logic input voltage	VIN(L)	-0.4	V	_
MO output voltage	VMO	6.0	V	_
LO0, LO1 output voltage	VLO	6.0	V	_
MO Inflow current	IMO	6.0	mA	_
LO0, LO1 Inflow current	ILO	6.0	mA	_
Power dissipation	P_{D}	1.2	W	(Note2)
Operating temperature	Topr	-40 to 85	°C	
Storage temperature	Tstg	-55 to 150	°C	_
Junction temperature	Tj(max)	150	°C	_

Note1: Usually, the maximum current value at the time should use 70% or less of the absolute maximum ratings for a standard on thermal rating. The maximum output current may be further limited in view of thermal considerations, depending on ambient temperature and board conditions.

Note2: Device alone (Ta =25°C)

When Ta exceeds 25°C, it is necessary to do the derating with 9.6 mW/°C.

Ta: Ambient temperature

Topr: Ambient temperature while the IC is active

Tj: Junction temperature while the IC is active. The maximum junction temperature is limited by the thermal shutdown (TSD) circuitry. It is advisable to keep the maximum current below a certain level so that the maximum junction temperature, Tj (MAX), will not exceed 120°C.

Caution) Absolute maximum ratings

The absolute maximum ratings of a semiconductor device are a set of ratings that must not be exceeded, even for a moment. Do not exceed any of these ratings.

Exceeding the rating (s) may cause device breakdown, damage or deterioration, and may result in injury by explosion or combustion.

The value of even one parameter of the absolute maximum ratings should not be exceeded under any circumstances. The TB67S128FTG does not have overvoltage detection circuit. Therefore, the device is damaged if a voltage exceeding its rated maximum is applied.

All voltage ratings, including supply voltages, must always be followed. The other notes and considerations described later should also be referred to.



16. Operation Ranges (Ta=-40 to 85°C)

Characteristics	Symbol	Min	Тур.	Max	Unit	Remarks
Motor power supply	VM	6.5	24	44	V	_
Motor output current	lout	_	3.0	5.0	Α	(Note1)
Louis input valtage	VIN(H)	2.0	_	5.5	V	Logic input H Level
Logic input voltage	VIN(L)	0	_	0.8	V	Logic input L Level
MO output pin voltage	VMO	_	3.3	5.0	V	_
LO0, LO1 output pin voltage	VLO	_	3.3	5.0	V	_
Clock input frequency	fCLK	_	_	200	kHz	_
Chopper frequency	fchop (range)	40	70	150	kHz	_
Vref input voltage	Vref	GND	2.0	3.6	V	_

Note1: Maximum current for actual usage may be limited by the operating circumstances such as operating conditions (exciting mode, operating time, and so on), ambient temperature, and heat conditions (board condition and so on).

17. Electrical Specifications 1 (Ta = 25°C, VM = 24 V, unless otherwise specified)

Characteristi	cs	Symbol	Test condition	Min	Тур.	Max	Unit
Landa lanaturakan	HIGH	VIN(H)	Logic input (Note1)	2.0	_	5.5	V
Logic input voltage	LOW	VIN(L)	Logic input (Note1)	0	_	0.8	V
Logic input hysteresis	s voltage	VIN(HYS)	Logic input (Note1)	100	_	300	mV
Logio input current	HIGH	IIN(H)	VIN(H) = 3.3 V	_	33	1	μΑ
Logic input current	LOW	IIN(L)	VIN(L) = 0 V	_	_	1	μΑ
MO output pin voltage	LOW	VOL(MO)	IOL = 5 mA, output = L	_	0.2	0.5	V
LO0, LO1 output pin voltage	LOW	VOL(LO)	IOL = 5 mA, output = L	_	0.2	0.5	V
Current consumption		IM1	Output pins = open Standby mode	_	1.8	3.2	mA
		IM2	Output pins = open ENABLE pin = L in releasing Standby mode	_	5.5	8.6	mA
		IM3	Output pins = open Full step resolution	_	8.2	10.4	mA
Output lookaga aurrant	High side	IOH	VM = 44 V, Vout = 0 V	_	_	1	μΑ
Output leakage current	Low side IOL VM = Vout = 44 V		-1	_	_	μΑ	
Motor current channel differential		∆lout1	Current differential between Ch	-5	0	5	%
Motor current setting	Motor current setting accuracy		lout =3.0 A	-5	0	5	%
RS pin currer	nt	IRS	VRS = 0 V	0		10	μΑ
Motor output ON res (High side+Lows		Ron(H+L)	Tj = 25°C, High side+Low side	_	0.25	0.35	Ω

Note: When the logic signal is applied to the device whilst the VM power supply is not asserted; the device is designed not to function, but for safe usage, please apply the logic signal after the VM power supply is asserted and the VM voltage reaches the proper operating range.

Note1: VIN(H) is defined as the VIN voltage that causes the outputs (OUT_A+ pin, OUT_A- pin, OUT_B+ pin, OUT_B- pin) to change when a pin under test is gradually raised from 0 V.VIN(L) is defined as the VIN voltage that causes the outputs (OUT_A+ pin, OUT_A- pin, OUT_B+ pin, OUT_B- pin) to change when the pin is then gradually lowered. The difference between VIN(H) and VIN(L) is defined as the VIN(HYS).



18. Electrical Specifications 2 (Ta =25°C, VM = 24 V, unless otherwise specified)

Characteristics	Symbol	Test condition	Min	Тур.	Max	Unit
Vref input current	Iref	Vref = 2.0 V	_	0	1	μΑ
VCC voltage	VCC	ICC = 5.0 mA	4.75	5	5.25	V
VCC current	ICC	VCC = 5.0 V	1	2.5	5	mA
Vref gain rate	Vref(gain)	Vref = 2.0 V GAIN_SEL pin = L	1/5.2	1/5	1/4.8	
Thermal shutdown (TSD) threshold (Note1)	TjTSD	_	145	160	175	°C
VM recovery voltage	VMR	_	5.7	6	6.3	V
Over current detection (ISD) threshold (Note2)	ISD	_	5.7	7.2	10	Α

Note1: About TSD

When the junction temperature of the device reaches the TSD threshold, the TSD circuit is triggered; the internal reset circuit then turns off the output transistors. Noise rejection blanking time is built-in to avoid misdetection. Once the TSD circuit is triggered, the device will be set to standby mode, and can be cleared by reasserting the VM power source, or setting the MODE pins to standby mode. The TSD circuit is a backup function to detect a thermal error, therefore is not recommended to be used aggressively.

Note2: About ISD

When the output current reaches the threshold, the ISD circuit is triggered; the internal reset circuit then turns off the output transistors. Once the ISD circuit is triggered, the device keeps the output off until power-on reset (POR), is reasserted or the device is set to standby mode by MODE pins. For fail-safe, please insert a fuse to avoid secondary trouble.

Back-EMF

While a motor is rotating, there is a timing at which power is fed back to the power supply. At that timing, the motor current recirculates back to the power supply due to the effect of the motor back-EMF.

If the power supply does not have enough sink capability, the power supply and output pins of the device might rise above the rated voltages. The magnitude of the motor back-EMF varies with usage conditions and motor characteristics. It must be fully verified that there is no risk that the TB67S128FTG or other components will be damaged or fail due to the motor back-EMF.

Cautions on Overcurrent Shutdown (ISD) and Thermal Shutdown (TSD)

The ISD and TSD circuits are only intended to provide temporary protection against irregular conditions such as an output short-circuit; they do not necessarily guarantee the complete IC safety.

If the device is used beyond the specified operating ranges, these circuits may not operate properly: then the device may be damaged due to an output short-circuit.

The ISD circuit is only intended to provide a temporary protection against an output short-circuit. If such a condition persists for a long time, the device may be damaged due to overstress. Overcurrent conditions must be removed immediately by external hardware.

IC Mounting

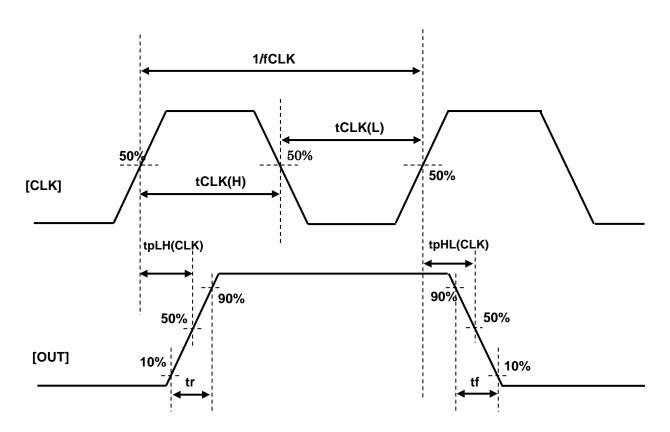
Do not insert devices incorrectly or in the wrong orientation. Otherwise, it may cause breakdown, damage and/or deterioration of the device.



19. AC Electrical Specification (Ta = 25°C, VM = 24 V, 6.8 mH/5.7 Ω)

Characteristics	Symbol	Test condition	Min	Тур.	Max	Unit
Inside filter of CLK input minimum High width	tCLK(H)	The CLK(H) minimum pulse width	300	_		ns
Inside filter of CLK input minimum Low width	tCLK(L)	tCLK(L) The CLK(L) minimum pulse width		_		ns
	tr		30	80	130	ns
Output transistor	tf		40	90	140	ns
switching specific	tpLH(CLK)	CLK output	_	1000	_	ns
	tpHL(CLK)	CLK output	_	1500	_	ns
Analog noise blanking time	AtBLK	VM = 24 V, lout = 3.0 A Analog tblank	250	400	550	ns
Oscillator frequency accuracy	ΔfOSCM	COSC = 270 pF, ROSC = 5.1 k Ω	-15	_	+15	%
Oscillator reference frequency	fOSCM	COSC= 270 pF, ROSC =5.1 kΩ	1020	1200	1380	kHz
Chopping frequency	fchop	Output: Active (lout = 1.5 A), fOSC = 1200 kHz	_	75		kHz

AC Electrical Specification Timing chart

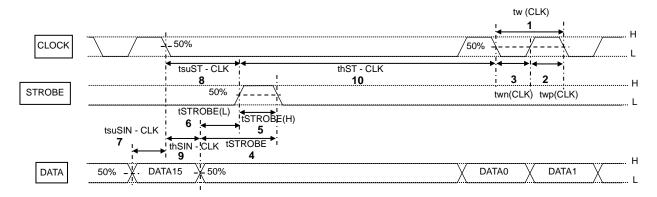


Note: Timing charts may be simplified for explanatory purpose.



20. Other AC Electrical Specification (Ta = 25°C, VM = 24 V, unless otherwise specified)

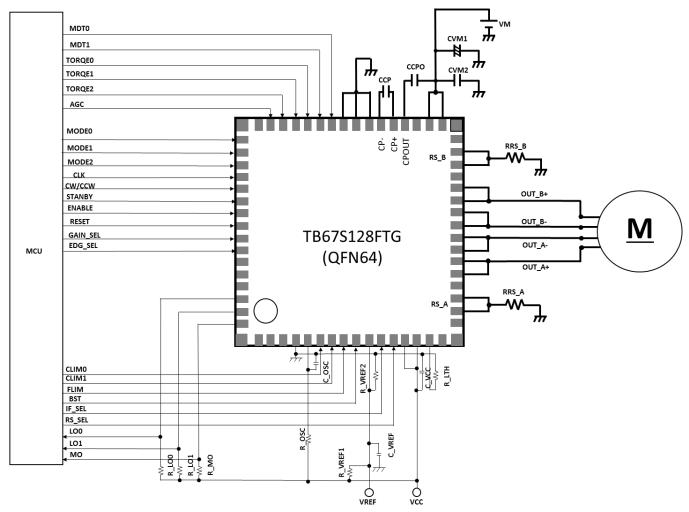
Characteristics	Symbol	Test condition	Min	Тур.	Max	Unit	No. in Timing Chart
Serial CLK frequency	fSCLK	VIN = 3.3 V	1.0	1	25	MHz	_
CLK Cycle	tsCKW	VIH = 3.3 V, VIL = 0 V, tr = tf = 23 ns	46			ns	_
Minimovina CLIZ mula a	tw(CLK)		40	1		ns	1
Minimum CLK pulse width	twp(CLK)	VIN = 3.3 V	20		1	ns	2
wiatri	twn(CLK)		20		1	ns	3
Minimum CTDODE mulas	tSTROBE		40		1	ns	4
Minimum STROBE pulse width	tSTROBE(H)	VIN = 3.3 V	20		1	ns	5
wiatri	tSTROBE(L)		20		1	ns	6
Data actus timo	tsuSIN - CLK	VIN = 3.3 V	10		1	ns	7
Data setup time	tsuST - CLK	VIIN = 3.3 V	10			ns	8
Data hold time	thSIN - CLK	VIN = 3.3 V	10			ns	9
Data 11010 time	thST - CLK	V IIV = 3.3 V	10	_	_	ns	10



Note: The CLK whose frequency is 1MHz or less may be used if the above conditions are met.



21. Application Circuit Example (RS_SEL pin = H, IF_SEL pin = L)



The application circuit shown in this document is provided for reference purposes only. The data for mass production are not guaranteed.

Component values (for reference only)

Part's symbol	Component	Reference component values
CVM1	Electrolytic capacitor	100 μF (CVM1 ≥ 10 μF)
CVM2	Ceramic capacitor	(0.1 μF)
CCP	Ceramic capacitor	0.022 μF
CCPO	Ceramic capacitor	0.22 μF
C_VCC	Ceramic capacitor	0.1 μF
R_OSC	Resistor	5.1 kΩ (1.8 kΩ to 8.2 kΩ)
C_OSC	Ceramic capacitor	270 pF
R_VREF1, R_VREF2	Resistor	Arbitrary (10 k Ω ≤ R_VREF1 + R_VREF2 ≤ 50 k Ω)
C_VREF	Ceramic capacitor	(0.1 μF)
R_MO	Resistor	10 kΩ (10 kΩ to 100 kΩ)
R_LO0, R_LO1	Resistor	10 kΩ (10 kΩ to 100 kΩ)
R_LTH	Resistor	100 kΩ

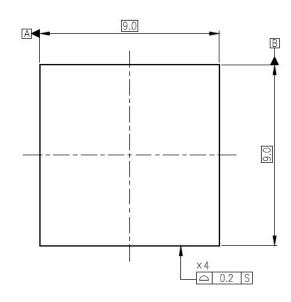
Note: Component values in above table are for reference only. Some components outside of the range can be adopted depending on the usage conditions.

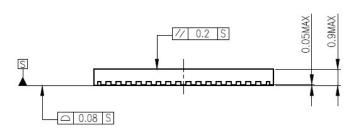


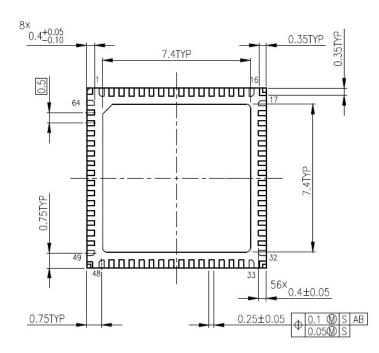
22. Package Dimensions

P-VQFN64-0909-0.50-006

Unit: mm







Weight: 0.229 g (typ.)



Notes on Contents

1. Block Diagrams

Some of the functional blocks, circuits, or constants in the block diagram may be omitted or simplified for explanatory purposes.

2. Equivalent Circuits

The equivalent circuit diagrams may be simplified or some parts of them may be omitted for explanatory purposes.

3. Timing Charts

Timing charts may be simplified for explanatory purposes.

4. Application Circuits

The application circuits shown in this document are provided for reference purposes only. Thorough evaluation is required, especially at the mass production design stage.

Providing these application circuit examples does not grant a license for industrial property rights.

5. Test Circuits

Components in the test circuits are used only to obtain and confirm the device characteristics. These components and circuits are not guaranteed to prevent malfunction or failure from occurring in the application equipment.



IC Usage Considerations

Notes on handling of ICs

- (1) The absolute maximum ratings of a semiconductor device are a set of ratings that must not be exceeded, even for a moment. Do not exceed any of these ratings.
 Exceeding the rating(s) may cause the device breakdown, damage or deterioration, and may result injury by explosion or combustion.
- (2) Use an appropriate power supply fuse to ensure that a large current does not continuously flow in case of over current and/or IC failure. The IC will fully break down when used under conditions that exceed its absolute maximum ratings, when the wiring is routed improperly or when an abnormal pulse noise occurs from the wiring or load, causing a large current to continuously flow and the breakdown can lead smoke or ignition. To minimize the effects of the flow of a large current in case of breakdown, appropriate settings, such as fuse capacity, fusing time and insertion circuit location, are required.
- (3) If your design includes an inductive load such as a motor coil, incorporate a protection circuit into the design to prevent device malfunction or breakdown caused by the current resulting from the inrush current at power ON or the negative current resulting from the back electromotive force at power OFF. IC breakdown may cause injury, smoke or ignition.

 Use a stable power supply with ICs with built-in protection functions. If the power supply is unstable, the protection function may not operate, causing IC breakdown. IC breakdown may cause injury, smoke or ignition.
- (4) Do not insert devices in the wrong orientation or incorrectly. Make sure that the positive and negative terminals of power supplies are connected properly. Otherwise, the current or power consumption may exceed the absolute maximum rating, and exceeding the rating(s) may cause the device breakdown, damage or deterioration, and may result injury by explosion or combustion. In addition, do not use any device that is applied the current with inserting in the wrong orientation or incorrectly even just one time.
- (5) Carefully select external components (such as inputs and negative feedback capacitors) and load components (such as speakers), for example, power amp and regulator.

 If there is a large amount of leakage current such as from input or negative feedback condenser, the IC output DC voltage will increase. If this output voltage is connected to a speaker with low input withstand voltage, overcurrent or IC failure may cause smoke or ignition. (The overcurrent may cause smoke or ignition from the IC itself.) In particular, please pay attention when using a Bridge Tied Load (BTL) connection-type IC that inputs output DC voltage to a speaker directly.



Points to remember on handling of ICs

(1) Over current Protection Circuit

Over current protection circuits (referred to as current limiter circuits) do not necessarily protect ICs under all circumstances. If the Over current protection circuits operate against the over current, clear the over current status immediately.

Depending on the method of use and usage conditions, such as exceeding absolute maximum ratings can cause the over current protection circuit to not operate properly or IC breakdown before operation. In addition, depending on the method of use and usage conditions, if over current continues to flow for a long time after operation, the IC may generate heat resulting in breakdown.

(2) Thermal Shutdown Circuit

Thermal shutdown circuits do not necessarily protect ICs under all circumstances. If the thermal shutdown circuits operate against the over temperature, clear the heat generation status immediately. Depending on the method of use and usage conditions, such as exceeding absolute maximum ratings can cause the thermal shutdown circuit to not operate properly or IC breakdown before operation.

(3) Heat Radiation Design

In using an IC with large current flow such as power amp, regulator or driver, please design the device so that heat is appropriately radiated, not to exceed the specified junction temperature (T_j) at any time and condition. These ICs generate heat even during normal use. An inadequate IC heat radiation design can lead to decrease in IC life, deterioration of IC characteristics or IC breakdown. In addition, please design the device taking into considerate the effect of IC heat radiation with peripheral components.

(4) Back-EMF

When a motor reverses the rotation direction, stops or slows down abruptly, a current flow back to the motor's power supply due to the effect of back-EMF. If the current sink capability of the power supply is small, the device's motor power supply and output pins might be exposed to conditions beyond absolute maximum ratings. To avoid this problem, take the effect of back-EMF into consideration in system design.



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